TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (π-MOSIII)

2SK2746

DC-DC Converter and Motor Drive Applications

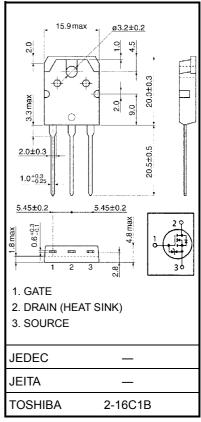
Unit: mm

• Low drain-source ON resistance : $RDS (ON) = 1.3 \Omega (typ.)$ • High forward transfer admittance : $|Y_{fs}| = 5.0 S (typ.)$ • Low leakage current : $IDSS = 100 \mu A (max) (VDS = 640 V)$

• Enhancement-mode : $V_{th} = 2.0 \sim 4.0 \text{ V (V}_{DS} = 10 \text{ V, I}_{D} = 1 \text{ mA})$

Maximum Ratings (Ta = 25°C)

Characteristics		Symbol	Rating	Unit	
Drain-source voltage		V_{DSS}	800	V	
Drain-gate voltage (R _{GS} = 20 kΩ)		V_{DGR}	800	V	
Gate-source voltage		V_{GSS}	±30	V	
Drain current	DC (Note 1)	I _D	7	Α	
	Pulse (Note 1)	I _{DP}	21	Α	
Drain power dissipation (Tc = 25°C)		P_{D}	150	W	
Single pulse avalanche energy (Note 2)		E _{AS}	673	mJ	
Avalanche current		I _{AR}	7	Α	
Repetitive avalanche energy (Note 3)		E _{AR}	15	mJ	
Channel temperature		T _{ch}	150	°C	
Storage temperature range		T _{stg}	-55~150	°C	



Weight: 4.6 g (typ.)

Thermal Characteristics

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	R _{th (ch-c)}	0.833	°C/W
Thermal resistance, channel to ambient	R _{th (ch-a)}	50	°C/W

Note 1: Please use devices on condition that the channel temperature is below 150°C.

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Note 2: V_{DD} = 90 V, T_{ch} = 25°C (initial), L = 24.9 mH, R_G = 25 Ω , I_{AR} = 7 A

Note 3: Repetitive rating: Pulse width limited by maximum channel temperature

This transistor is an electrostatic sensitive device.

Please handle with caution.



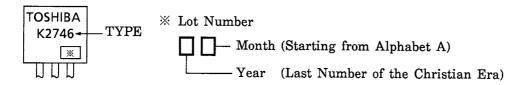
Electrical Characteristics (Ta = 25°C)

Charac	eteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	rrent	I _{GSS}	V _{GS} = ±30 V, V _{DS} = 0 V	_	_	±10	μΑ
Gate-source bre	eakdown voltage	V _(BR) GSS	$I_G = \pm 10 \ \mu A, \ V_{DS} = 0 \ V$	±30	_	1	V
Drain cut-off cu	rrent	I _{DSS}	V _{DS} = 640 V, V _{GS} = 0 V	_	_	100	μA
Drain-source br	eakdown voltage	V _{(BR)DSS}	I_D = 10 mA, V_{GS} = 0 V	800	_	_	V
Gate threshold v	oltage	V_{th}	V _{DS} = 10 V, I _D = 1 mA	2.0	_	4.0	V
Drain-source O	N resistance	R _{DS} (ON)	V _{GS} = 10 V, I _D = 3.5 A	_	1.3	1.7	Ω
Forward transfer	admittance	Y _{fs}	V _{DS} = 20 V, I _D = 3.5 A	1.25	5.0	_	S
Input capacitano	е	C _{iss}		_	1500	_	
Reverse transfer	r capacitance	C _{rss}	V _{DS} = 25 V, V _{GS} = 0 V, f = 1 MHz	_	30	_	pF
Output capacitance		C _{oss}			140	_	
Switching time	Rise time	t _r	$V_{GS} \stackrel{10 \text{ V}}{\circ} V \stackrel{\text{I}_{D} = 3.5 \text{ A}}{\circ} V_{OUT}$ $R_{L} = 114 \Omega$ $V_{DD} = 400 \text{ V}$	_	35	_	
	Turn-on time	t _{on}		_	80	ı	ne
	Fall time	t _f		_	50	ı	- ns
	Turn-off time	t _{off}	Duty \leq 1%, $t_{\rm w} = 10 \ \mu \rm s$	_	220	_	
Total gate charg plus gate-drain)	9 ,			55	_	nC	
Gate-source charge		Q _{gs}	$V_{DD} \approx 400 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 7 \text{ A}$		30		_
Gate-drain ("miller") Charge		Q_{gd}			25		_

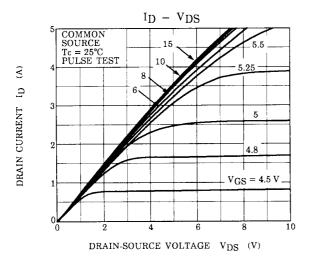
Source-Drain Ratings and Characteristics (Ta = 25°C)

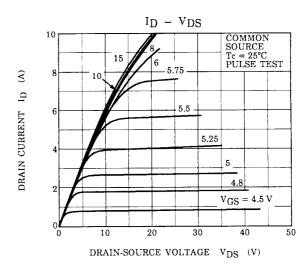
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I _{DR}	_	_	_	7	Α
Pulse drain reverse current (Note 1)	I _{DRP}	_	_	_	21	Α
Forward voltage (diode)	V _{DSF}	I _{DR} = 7 A, V _{GS} = 0 V	_	_	-1.9	V
Reverse recovery time	t _{rr}	$I_{DR} = 7 \text{ A}, V_{GS} = 0 \text{ V}, dI_{DR} / dt = 100 \text{ A} / \mu \text{s}$	_	1300	_	ns
Reverse recovery charge	Q _{rr}		_	14	_	μC

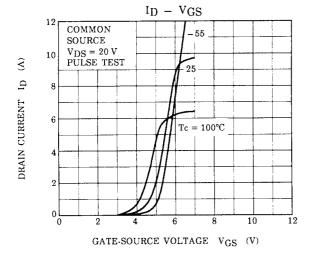
Marking

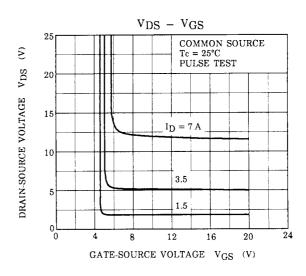


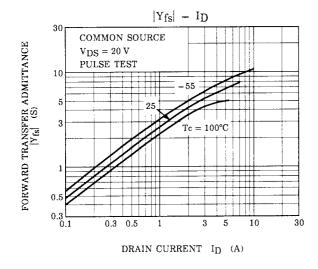
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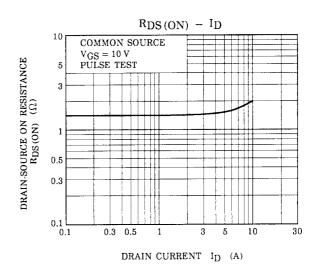




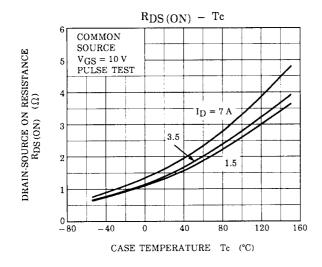


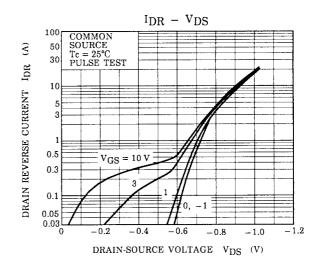


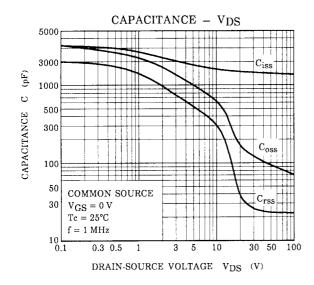


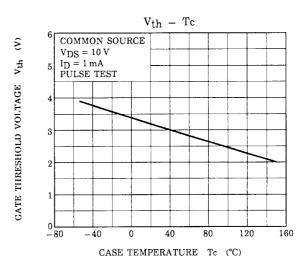


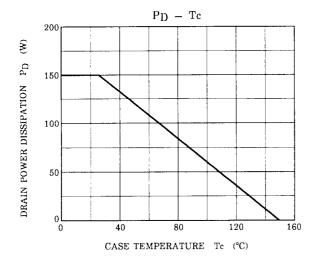
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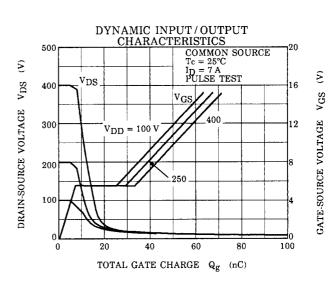




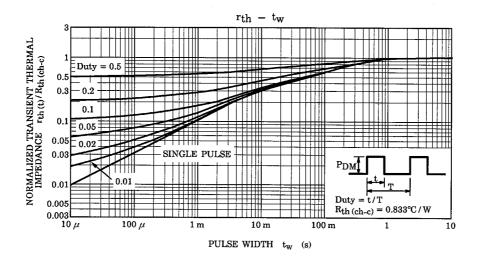


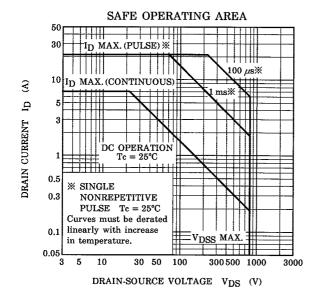


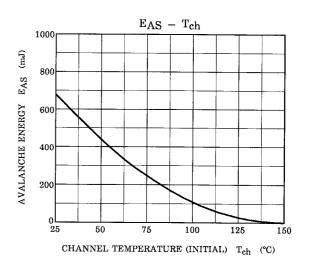


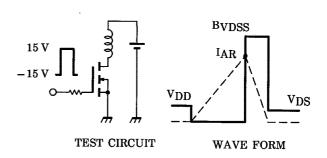


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$$R_G$$
 = 25 Ω
 V_{DD} = 90 V, L = 24.9 mH

$$E_{AS} = \frac{1}{2} \cdot L \cdot I^{2} \cdot \left(\frac{B_{VDSS}}{B_{VDSS} - V_{DD}} \right)$$

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